



Session Title:	[MC2] CMP Challenges for the Next Generation Devices
Session Date:	November 20 (Mon.), 2023
Session Time:	14:55-16:35
Session Room:	Room C (Grand Ballroom 2, 2F)
Session Chair:	Prof. Jihoon Seo (Clarkson Univ., USA)

[MC2-1] [Invited]

14:55-15:25

CMP Challenges and Opportunities for the Next Generation Devices

Hoyoung Kim (Samsung Electronics Co., Ltd., Korea)

[MC2-2]

15:25-15:45

Effect of Organic Amine on Ceria Contamination for Nitride Surface During STI CMP

Muskan Dogra, Young-Jung Kim, Tae-Gon Kim, and Jin-Goo Park (Hanyang Univ., Korea)

[MC2-3]

15:45-16:05

Effect of Pad Topography with Engineered Surfaces on Removal Rate in CMP

Youngwook Park, Hokyoung Jung, Taekyoung Lee, Hyoungjae Kim (KITECH, Korea), and Haedo Jeong (Pusan Nat'l Univ., Korea)

[MC2-4] [Invited]

16:05-16:35

Surface Modified Nanoparticle Abrasives for Efficient CMP Process

Tae-Dong Kim (Hannam Univ., Korea)